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# FQP9N50

#### 500V N-Channel MOSFET

#### **General Description**

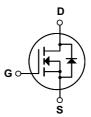
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, power factor correction, electronic lamp ballast based on half bridge.

#### **Features**

- 9.0A, 500V,  $R_{DS(on)}$  = 0.73 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 28 nC)
- Low Crss (typical 20 pF)
- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQP9N50	Units
V <sub>DSS</sub>	Drain-Source Voltage		500	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C	<b>(</b> )	9.0	Α
	- Continuous (T <sub>C</sub> = 100°	(C)	5.7	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	36	А
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	360	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	9.0	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	14.7	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)		147	W
	- Derate above 25°C		1.18	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.85	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	500			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.55		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V			1	μΑ
		V <sub>DS</sub> = 400 V, T <sub>C</sub> = 125°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.5 A		0.58	0.73	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 4.5 A (Note 4)		8.2		S
C <sub>oss</sub> C <sub>rss</sub>	Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz		160	210	pF
C <sub>rss</sub>	Reverse Transfer Capacitance					_
				20	30	pF
Switch	ing Characteristics			20	30	pF
	ing Characteristics  Turn-On Delay Time	Vpp = 250 V lp = 9.0 A.		25	60	pF
t <sub>d(on)</sub>		$V_{DD} = 250 \text{ V}, I_{D} = 9.0 \text{ A},$ $R_{G} = 25 \Omega$		I.	1	
t <sub>d(on)</sub>	Turn-On Delay Time	$R_G = 25 \Omega$		25	60	ns
$t_{d(on)}$ $t_r$ $t_{d(off)}$	Turn-On Delay Time Turn-On Rise Time			25 95	60 200	ns ns
$t_{d(on)}$ $t_r$ $t_{d(off)}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time	$R_G = 25 \Omega$		25 95 55	60 200 120	ns ns ns
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$ $Q_g$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	$R_G$ = 25 Ω (Note 4, 5)	  	25 95 55 60	60 200 120 130	ns ns ns
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$ $Q_g$ $Q_{gs}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge	$R_G = 25 \Omega$ (Note 4, 5) $V_{DS} = 400 \text{ V}, I_D = 9.0 \text{ A},$	   	25 95 55 60 28	60 200 120 130	ns ns ns ns
t <sub>d(on)</sub> t <sub>r</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$R_G = 25 \ \Omega$ (Note 4, 5) $V_{DS} = 400 \ V, \ I_D = 9.0 \ A, \ V_{GS} = 10 \ V$ (Note 4, 5)	   	25 95 55 60 28 7.0	60 200 120 130 36	ns ns ns ns
$egin{array}{l} t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ Q_g \\ Q_{gs} \\ Q_{gd} \\ egin{array}{c} Q_{gd} \\ egin{array}{c} Drain-S \\ \end{array}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$R_G = 25~\Omega \label{eq:RG}$ (Note 4, 5) $V_{DS} = 400~V,~I_D = 9.0~A,~V_{GS} = 10~V \label{eq:VDS}$ (Note 4, 5) and Maximum Ratings	   	25 95 55 60 28 7.0	60 200 120 130 36 	ns ns ns ns nC
t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub> Drain-S	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics and Maximum Continuous Drain-Source Diode	$R_G$ = 25 $\Omega$ (Note 4, 5) $V_{DS}$ = 400 V, $I_D$ = 9.0 A, $V_{GS}$ = 10 V (Note 4, 5) and Maximum Ratings of the Forward Current	    	25 95 55 60 28 7.0 12.5	60 200 120 130 36 	ns ns ns nc nC nC
$egin{array}{l} t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ Q_g \\ Q_{gs} \\ Q_{gd} \\ \hline egin{array}{c} Drain-S \\ I_S \\ I_{SM} \\ \end{array}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics as Maximum Continuous Drain-Source Diode Fall Time	$R_G$ = 25 $\Omega$ (Note 4, 5) $V_{DS}$ = 400 V, $I_D$ = 9.0 A, $V_{GS}$ = 10 V (Note 4, 5)  and Maximum Ratings  de Forward Current  forward Current	     	25 95 55 60 28 7.0 12.5	60 200 120 130 36  	ns ns ns nc nC nC
t <sub>d(on)</sub> t <sub>r</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics and Maximum Continuous Drain-Source Diode	$R_G$ = 25 $\Omega$ (Note 4, 5) $V_{DS}$ = 400 V, $I_D$ = 9.0 A, $V_{GS}$ = 10 V (Note 4, 5) and Maximum Ratings of the Forward Current		25 95 55 60 28 7.0 12.5	60 200 120 130 36 	ns ns ns ns nC nC

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 8mH, I<sub>AS</sub> = 9.0A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25  $\Omega$ , Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  9.0A, di/dt  $\leq$  200A/μs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width  $\leq$  300μs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

# **Typical Characteristics**

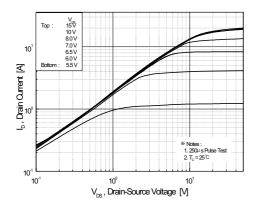


Figure 1. On-Region Characteristics

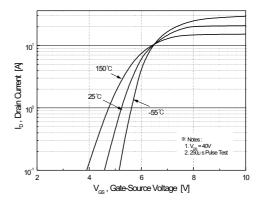


Figure 2. Transfer Characteristics

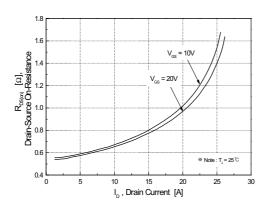


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

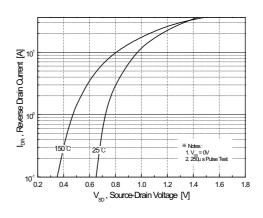


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

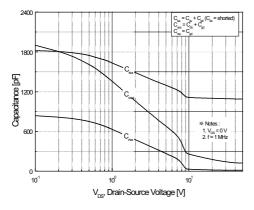


Figure 5. Capacitance Characteristics

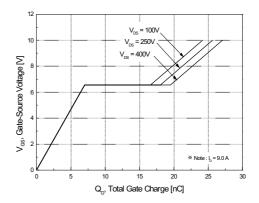


Figure 6. Gate Charge Characteristics

# Typical Characteristics (Continued)

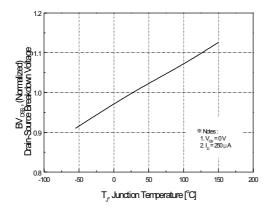
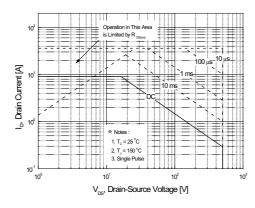


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



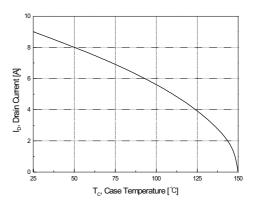


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

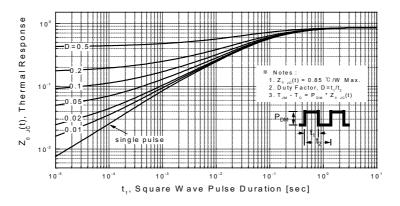
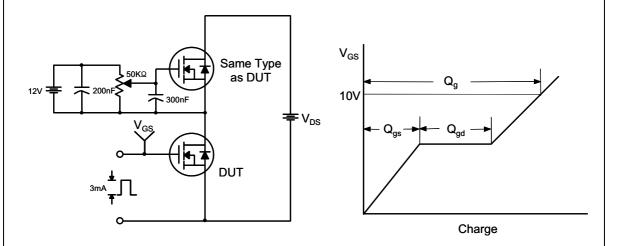


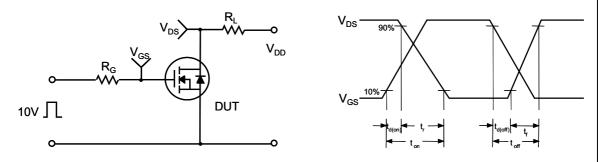
Figure 11. Transient Thermal Response Curve

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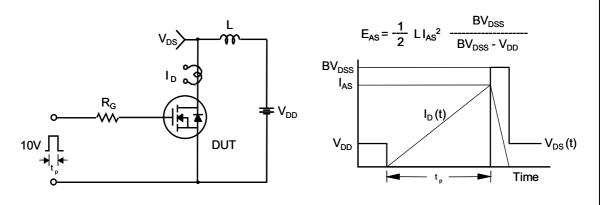
#### **Gate Charge Test Circuit & Waveform**



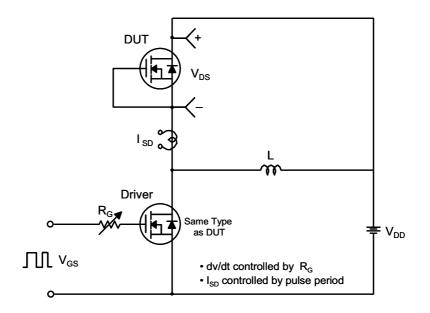
#### **Resistive Switching Test Circuit & Waveforms**

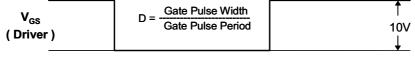


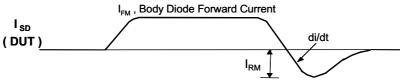
#### **Unclamped Inductive Switching Test Circuit & Waveforms**



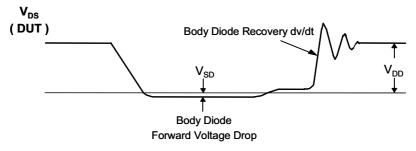
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms





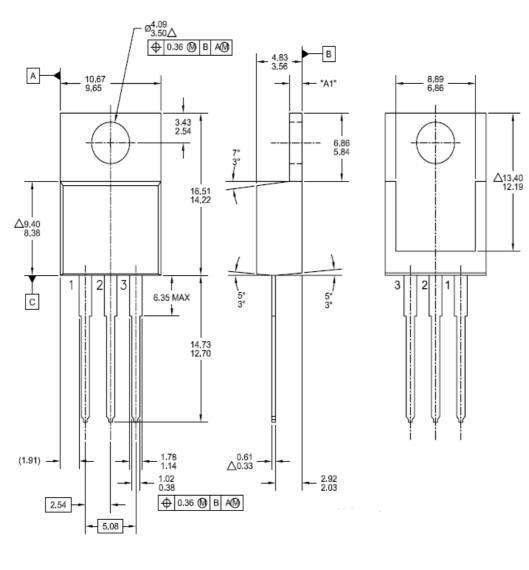


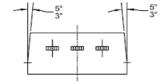
Body Diode Reverse Current



### **Mechanical Dimensions**

TO - 220





Dimensions in Millimeters

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